TOSHIBA Infrared LED GaAłAs Infrared Emitter

T L N 2 3 3

Rating

100

1000

200

4

-25~85 -30~100

260

(Note 1)

Unit

mΑ

mΑ

mW

V

°C

°C

°C

Infrared LED for Space-Optical-Transmission

- High radiant intensity: 80 mW/sr (typ.) at $I_F = 50$ mA
- Half-angle value: θ ¹/₂ = ±13° (typ.)
 A light source for remote control
- Wireless AV-signal transmission purpose
- High speed data transmission purpose

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Maximum Ratings (Ta = 25°C)

Characteristics

Forward current

Power dissipation

Reverse voltage

Pulse forward current

Operating temperature range

Storage temperature range

Soldering temperature (5 s), (Note 2)

Note 2: Soldering must be performed under the stopper.

Optical and Electrical Characteristics (Ta = 25°C)

Pin Connection

1. Anode 1 0 → 0 2 2. Cathode

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	VF	I _F = 100 mA	_	1.6	2.0	V
Reverse current	I _R	$V_R = 4 V$			60	μΑ
Radiant intensity	ΙE	I _F = 50 mA	46	80	_	mW/sr
Radiant power	PO	I _F = 50 mA	_	30	_	mW
Cut-off frequency	f _c	$I_{F} = 50 \text{ mA} + 5 \text{ mA}_{P-P} \qquad (\text{Note 3})$	_	15		MHz
Peak emission wavelength	λP	I _F = 50 mA	_	870	_	nm
Half-angle value	$\theta \frac{1}{2}$	I _F = 50 mA		±13	_	o

Note 3: Frequency when modulation light power decreases by 3dB from 1 MHz.

Symbol

 I_{F}

 I_{FP}

 P_D

 V_{R}

Topr

T_{stg}

T_{sol}

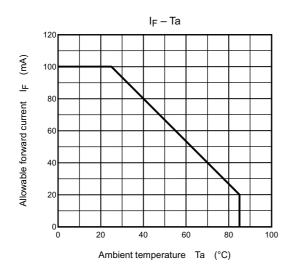
Handling Precautions

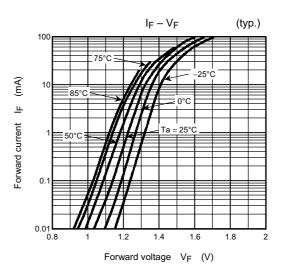
- Soldering must be performed under the stopper.
- When forming the leads, bend each lead under the 5 mm of package body. Soldering must be performed after the leads have been formed.
- The radiant intensity decrease over time due to current flowing in the infrared LED. When designing circuits, the device must take into account the change in radiant intensity over time. The change in radiant intensity is equal to the reciprocal of the change in LED infrared optical output.

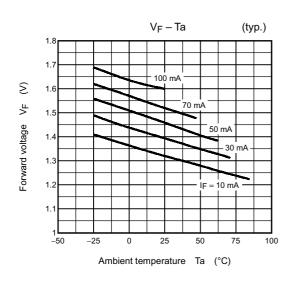
$$\frac{\mathrm{IE}(\mathrm{t})}{\mathrm{IE}(\mathrm{0})} = \frac{\mathrm{P}_{\mathrm{O}}(\mathrm{t})}{\mathrm{P}_{\mathrm{O}}(\mathrm{0})}$$

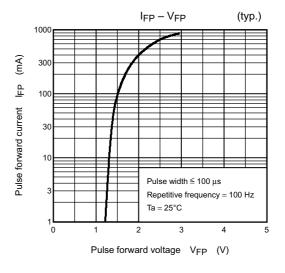
Unit: mm

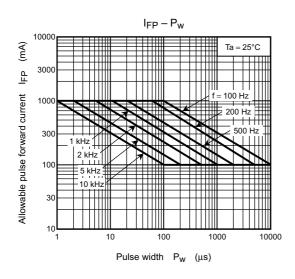
TOSHIBA

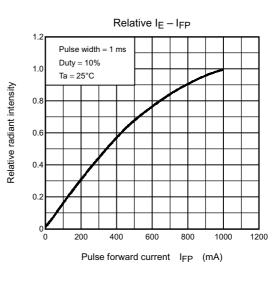


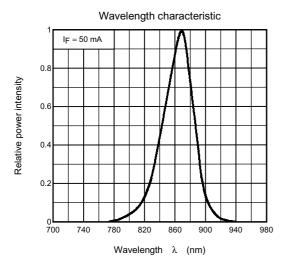


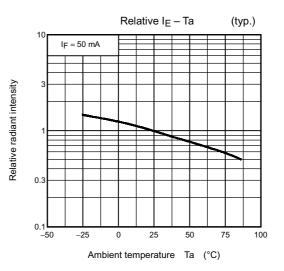


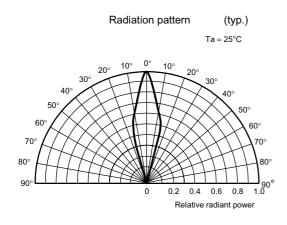












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